Rebound Electronics

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Market Insights Q3 2024

Disruptions Due to Hurricane Helene

Hurricane Helene Disrupts Quartz Production in North Carolina, Poses Challenges to Semiconductor Supply Chain

Hurricane Helene has impacted Spruce Pine, North Carolina, a key source of ultra-pure quartz essential for semiconductor manufacturing. Both Sibelco and The Quartz Corp, which operate the town's quartz mines, have suspended operations indefinitely due to the storm. This quartz is crucial for producing the crucibles used in the fabrication of silicon chips, solar panels, and fiber-optic cables. Nearby semiconductor manufacturers, such as Renesas Electronics in Durham, North Carolina, may feel indirect effects from the disruption. Currently, efforts are focused on ensuring the safety of employees and addressing damage to the region's infrastructure.

With Spruce Pine supplying up to 90% of the quartz used in global chip production, the temporary halt raises concerns about potential supply chain disruptions, particularly as demand for semiconductors continues to rise. Experts caution that extended downtime could affect the cost and availability of chips, which are fundamental to a wide range of technologies. While recovery efforts are progressing, local officials have emphasized the critical importance of resuming operations, given the region's reliance on the mining industry for its economic stability.

TE Connectivity Production Disruption Due to Hurricane Damage

TE Connectivity (TE) has suspended operations at its manufacturing site in Fairview, North Carolina, following severe damage caused by a recent hurricane. The storm disrupted essential services, including power, water, and telecommunications, making it necessary for TE to halt production activities at the facility. The company is prioritizing the safety and well-being of its employees while actively working to assess damage and implement measures to resume operations as soon as it is safe to do so. As a result of the temporary closure, TE has informed its customers that they may experience delays in the delivery of products assembled at this site. The company is committed to providing updated product lead times and revised order schedules as it continues recovery efforts.

The incident has been classified as a Force Majeure event under TE’s agreements with its customers and their affiliates, as it was both unforeseeable and beyond the company’s control. TE has stated that these circumstances render its performance commercially impractical and, as such, the company cannot accept responsibility for any additional costs customers may incur due to delays, such as line-down charges. Despite these challenges, TE remains committed to supporting its customers and ensuring the highest quality of service as it works to restore full production capabilities. Customers seeking updates or information regarding their orders are encouraged to contact their respective TE sales representatives for further assistance.

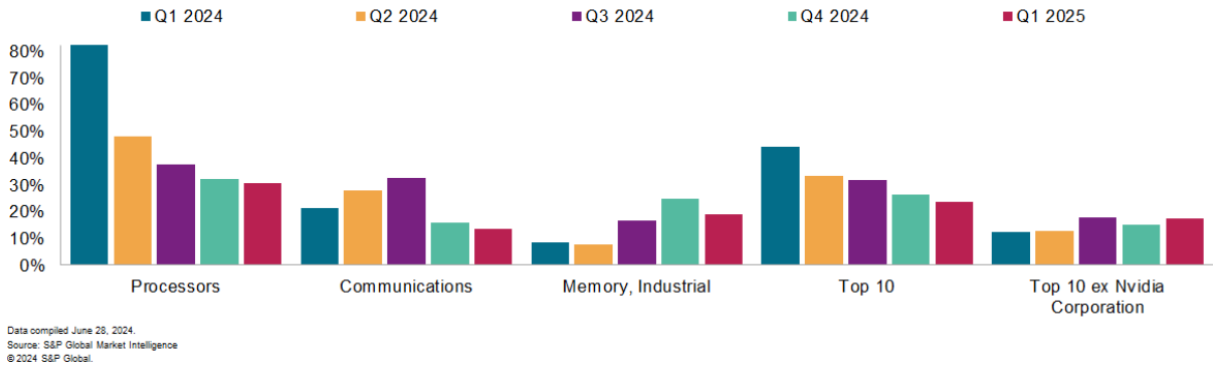
General Market Insight

Semiconductor Supply Chain Q3 2024

The semiconductor supply chain is experiencing a mixed recovery in Q3 2024, with growth in AI and auto sectors but slower progress in consumer devices. Mainland Chinese chipmakers face challenges like low production yields, despite advancements. Export controls by the US, EU, and Japan further constrain supply chains, especially impacting chipmakers reliant on China, which accounts for 30% of their sales. Analysts reported a 44% YoY revenue growth for top chip producers in Q1 2024, indicating overall recovery despite geopolitical pressures.

Recovery at Different Speeds Across Segments

The semiconductor industry is experiencing a multispeed recovery across different segments. AI processors have shown the fastest growth, with a forecasted slowdown to 31% in Q1 2025 from 82% in Q1 2024, still outpacing memory and communications chips. Consumer devices, like smartphones and PCs, reflect varied upgrade cycles, impacting their recovery. Export data shows a 7.9% year-over-year increase in smartphone shipments by May 2024, though overall exports of semiconductor-using consumer goods fell by 0.6%, highlighting mixed sector performance.



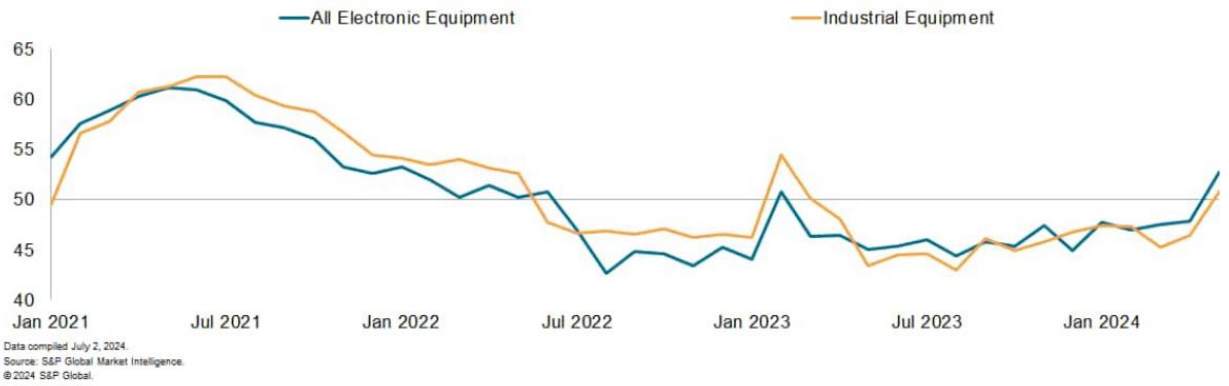
Source: S&P Global Market Intelligence Q3 2024

Challenges in the Industrial and Automotive Sectors

The industrial equipment and automotive sectors are lagging other semiconductor supply chains, despite some growth in May 2024, as indicated by the S&P Global Manufacturing New Orders Index. Challenges include high interest rates affecting capital expenditures and lingering chip inventories. Industrial equipment, typically slower to recover, faces a delayed upgrade cycle, while the automotive sector struggles with slowing demand growth for electric vehicles. Many industrial chipmakers remain cautious due to these economic pressures.

General Market Insight

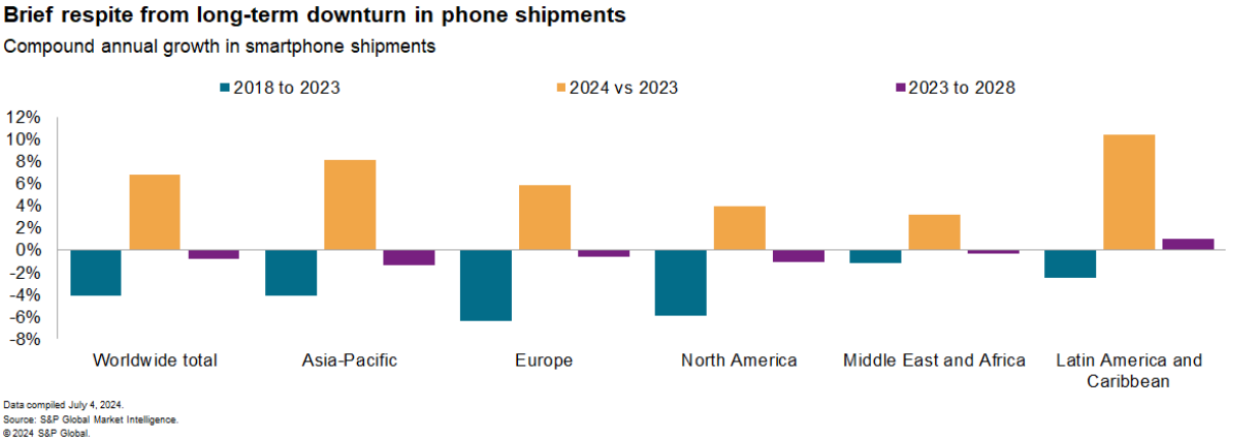
Semiconductor Industry Market Outlook



Source: S&P Global Market Intelligence Q3 2024

Trends in the Consumer Electronics Market

The consumer electronics market is seeing a temporary rise in smartphone shipments, expected to increase by 10.4% in 2024, driven by pent-up demand and new AI-focused products. However, longer replacement cycles and market saturation may hinder long-term growth. PC shipments are set for a new upgrade cycle, aided by AI-enabled models. Other connected devices, such as streaming media players and video game consoles, continue to decline, with streaming device shipments down 6.5% and game consoles dropping 32.3% year-over-year in early 2024.



Source: S&P Global Market Intelligence Q3 2024

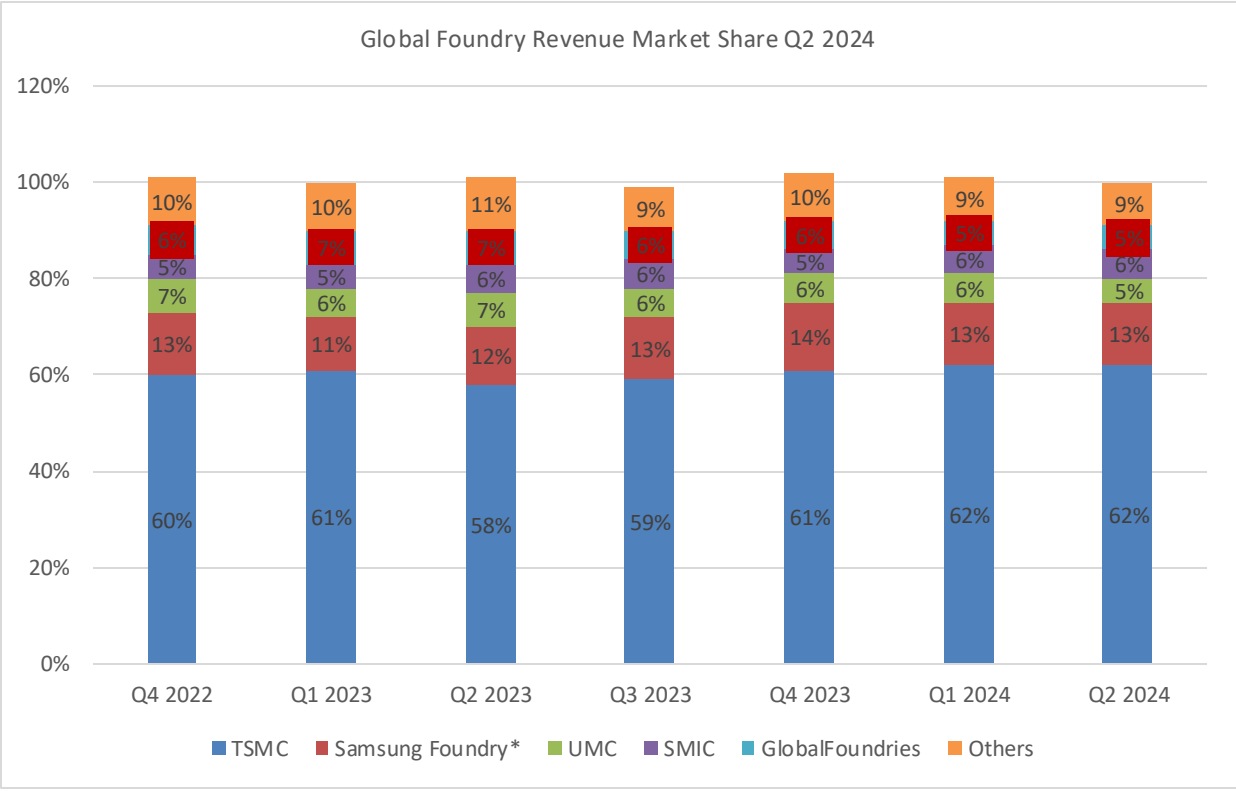
General Market Insight

Semiconductor Industry Market Outlook

Global Semiconductor Equipment Billings Hit $53.2 Billion in H1 2024 Amid Strong Industry Growth

Global semiconductor equipment billings reached $53.2 billion in the first half of 2024, reflecting strong industry growth. According to SEMI President and CEO Ajit Manocha, this rebound is driven by strategic investments aimed at meeting the rising demand for advanced technologies and supporting regional chipmaking ecosystems.

Global Foundry Revenue Market Share Q2 2024



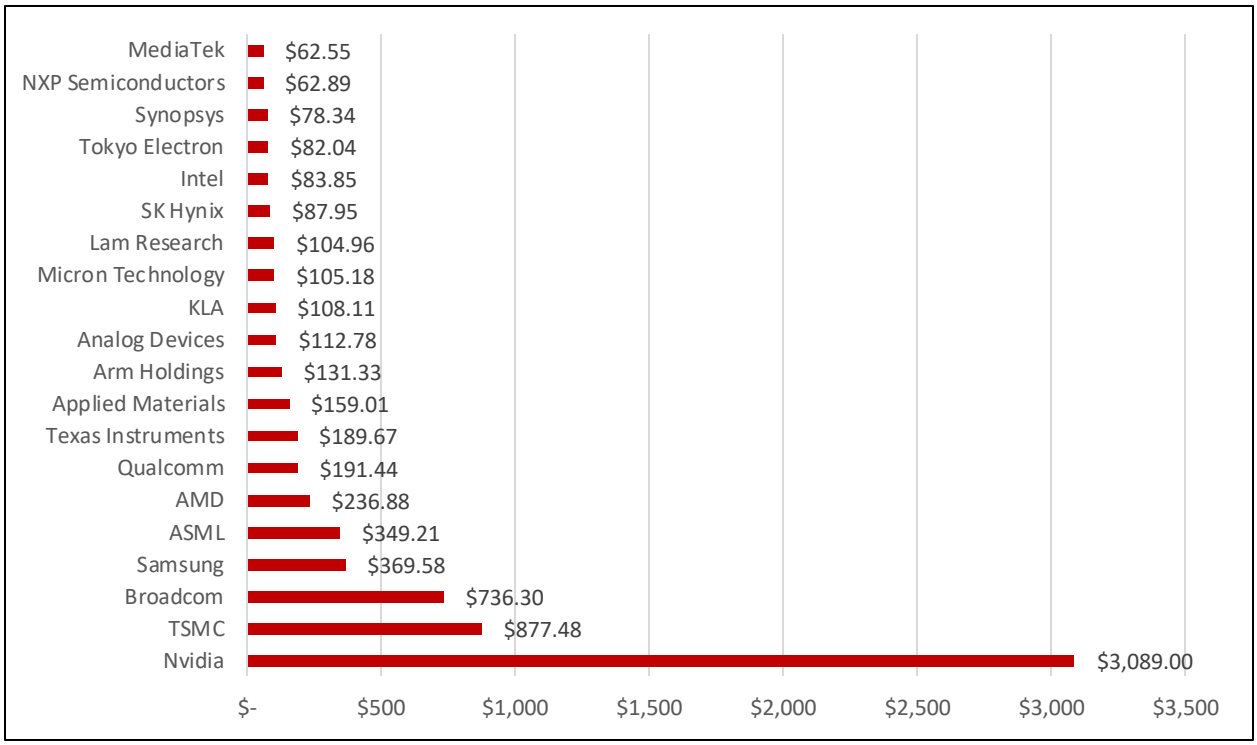
Key take aways:

- TSMC saw a 13.6% revenue rise in Q2 2024 due to strong demand for 5nm and 3nm tech.
- Q3 revenue is projected at $22.4-$23.2 billion, with gross margins of 54.5%.
- Full-year revenue guidance increased to 25% YoY, and Capex raised to $30-32 billion.
- AI chip demand may drive further price increases for advanced nodes.
- UMC reported a strong 35% gross margin in Q2 2024.
- Mature node demand remains uncertain due to cautious inventory management by end customers.

General Market Insight

Semiconductor Industry Market Outlook

Leading Semiconductor Companies Worldwide by Market Capitalization as of August 2024 (in Billion US Dollars)



Source: Statista August 2024

As of August 29, 2024, Nvidia led the semiconductor industry with a market capitalization of $3.09 trillion, followed by TSMC, Broadcom, Samsung, and ASML. The industry is dominated by companies from North America and Asia-Pacific, with Europe focusing on growing its semiconductor presence, especially in automotive chips. The EU aims to produce 20% of the world's semiconductors by 2030, leveraging firms like NXP and Infineon in the automotive sector. ASML, based in Europe, remains the only producer of EUV lithography machines.

General Market Insight

Semiconductor Industry Market Outlook

Global Semiconductor Manufacturing Industry Q2 2024 at a glance

The global semiconductor manufacturing industry in Q2 2024 showed notable improvement with significant growth in integrated circuit (IC) sales and stable capital expenditure. A surge in demand for AI chips and high-bandwidth memory (HBM) drove growth despite slower recoveries in some end markets. Key highlights include:

IC Sales Growth

IC sales saw a robust 27% year-over-year (YoY) growth in Q2 2024 and are projected to grow by 29% in Q3, surpassing record levels of 2021.

Wafer Fab Capacity

Installed wafer fab capacity increased to 40.5 million wafers per quarter and is expected to grow 1.6% in Q3, driven by advanced node developments in foundry and logic-related sectors.

Capital Expenditure

Despite a conservative start in 2024, semiconductor capital expenditures are expected to rise, led by a 16% increase in memory CapEx in Q3, in response to growing AI chip demand.

Seasonality Impact

Electronics sales faced a 0.8% YoY decline in the first half of 2024 but are forecasted to rebound by 4% YoY in Q3 as consumer demand recovers.
The SMM report also forecasts ongoing growth in the semiconductor manufacturing ecosystem, supported by AI and HBM demand.

General Market Insight

Semiconductor Industry Market News

Intel Falls Behind as Nvidia and AI Demand Dominate U.S. Semiconductor Market in Q3 2024

In Q3 2024, Nvidia surged ahead of Intel in semiconductor revenue, driven by the high demand for AI processors, while memory chip makers like SK Hynix and Samsung benefited from strong AI-related sales. Broadcom also outperformed Intel, thanks to its diversified semiconductor and software portfolio. Additionally, the U.S. strengthened its semiconductor industry through a new partnership with India, aimed at building a national security-focused chip fabrication plant

Europe’s Semiconductor Industry Thrives in Q3 2024 Amid Global Slowdown

In Q3 2024, Europe's semiconductor industry made significant strides, highlighted by TSMC’s new $3.9 billion plant in Dresden, Germany, aimed at boosting Europe's chip production for the automotive sector. The region outpaced the U.S. and Asia in market growth, even as other regions experienced declines. Major European companies like Infineon and STMicroelectronics continued to innovate, focusing on next-generation technologies like silicon carbide and gallium nitride, essential for electric vehicles and renewable energy. Additionally, ASML's advanced lithography systems are positioning Europe at the forefront of cutting-edge chip development

India's Semiconductor Ambitions Surge in Q3 2024 with Major Investments and Global Partnerships

In Q3 2024, India has made significant strides in its semiconductor industry, driven by several high-profile investments and government-backed initiatives. One of the major developments includes the construction of India's first semiconductor wafer fabrication plant in Dholera, Gujarat, a $10.9 billion joint venture between Tata Electronics and Powerchip Semiconductor Manufacturing Corporation (PSMC) from Taiwan. This plant aims to produce chips for various applications including automotive, AI, and communications.

Additionally, India is expanding its semiconductor testing and packaging capacity with new Outsourced Semiconductor Assembly and Test (OSAT) facilities in Morigaon, Assam, and Sanand, Gujarat. These facilities, set up in partnership with global players like Renesas (Japan) and Stars Microelectronics (Thailand), are expected to produce millions of chips per day.

Through the Semicon India Mission, the government has committed over $9 billion to create a robust semiconductor ecosystem, offering financial incentives and infrastructure support to attract both domestic and foreign players.

India's ambition is to secure a place among the top five semiconductor manufacturing countries by 2029

General Market Insight

Semiconductor Industry Market News

Asia-Pacific's Semiconductor Powerhouses: Navigating Growth and Competition in Q3 2024

- Taiwan remains at the forefront, largely due to TSMC's dominance in advanced semiconductor manufacturing. Taiwan continues to consolidate its role in producing cutting-edge chips, with a focus on high-performance technologies like 2-3 nm processes. The government has been fostering a supportive environment with subsidies and infrastructure, ensuring Taiwan's leadership in the global chip race despite geopolitical pressures

- In South Korea, semiconductor manufacturing is driven by giants like Samsung and SK Hynix. South Korea has been implementing its "K-Semiconductor Strategy," a massive $450 billion plan to bolster its semiconductor supply chain by 2030. This initiative aims to reduce dependency on imports and solidify its leadership in memory chip production

- Japan is making a comeback in the semiconductor space with significant government backing. A notable move includes a $3.9 billion subsidy for Rapidus, a company expected to produce 2 nm chips by 2027. Japan's partnerships with TSMC and other global players are further strengthening its manufacturing capabilities

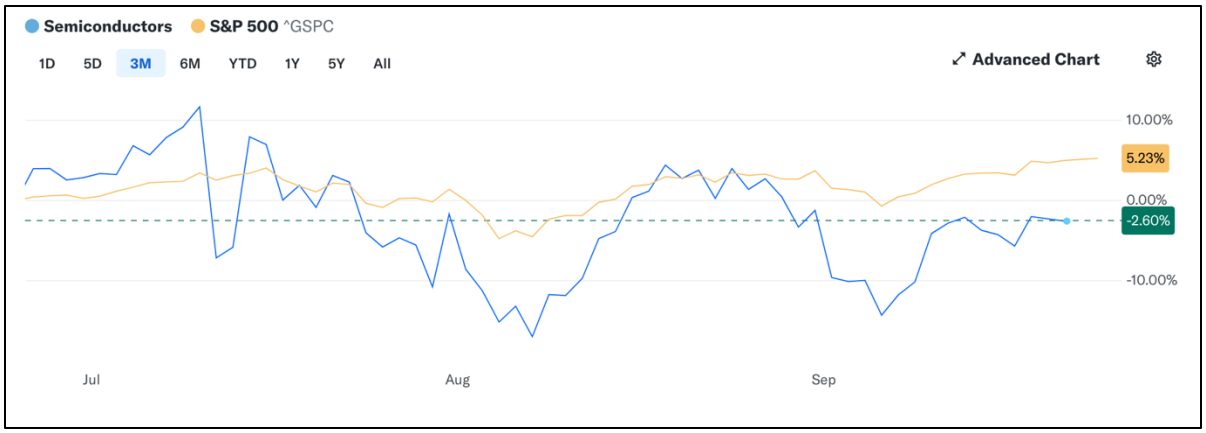
- Malaysia is positioning itself as a major semiconductor hub, focusing on expanding its capabilities beyond traditional assembly and testing. The Malaysian government launched a National Semiconductor Strategy aimed at attracting $107 billion in investments. This plan includes building local expertise in chip design and advanced packaging, key areas for future growth

- Vietnam and Indonesia are also increasing their presence in the global semiconductor supply chain by offering incentives and fostering investment in chip manufacturing

General Market Insight

Semiconductor Industry Stocks

Semiconductor Industry Overview (July – September 2024)



Source: Yahoo Finance, September 2024

Largest Companies in the Industry Q3 2024

Name	Last Price	1Y Target Est.	Market Weight	Market Cap	Day Change %	YTD Return
NVIDIA	120.88	145.22	58.34%	2.965T	3.97%	144.09%
Broadcom	174.84	192.71	16.07%	816.604B	1.10%	56.63%
AMD	158.32	185.99	5.04%	256.238B	1.00%	7.40%
Texas Instruments	204.94	206.03	3.68%	187.12B	0.53%	20.23%
QUALCOMM	166.95	211.47	3.66%	185.982B	0.60%	15.43%
Analog Devices	227.33	255.43	2.22%	112.868B	0.58%	14.49%
Micron Technology	94.03	156.01	2.05%	104.265B	0.49%	10.18%
Intel Corporation	22.81	25.59	1.92%	97.536B	1.11%	-54.61%
Marvell Technology	71.2	92.11	1.21%	61.673B	-0.85%	18.06%
NXP Semiconductors	233.75	293.29	1.17%	59.544B	0.82%	1.77%

Source: Yahoo Finance, September 2024

General Market Insight

Semiconductor Industry Fueled by AI and Automotive Innovations for Continued Growth

In Q2 2024, the semiconductor industry experienced strong growth, with sales up by 27%, driven largely by the rising demand for artificial intelligence (AI) and high-bandwidth memory (HBM). Despite challenges like Intel's stock drop, the broader market showed resilience, with forecasts predicting further growth in Q3. AI's influence is also boosting memory demand, pushing capital expenditures in the semiconductor sector.

Beyond memory, the automotive industry is fueling significant growth in passive components and LEDs. As electric vehicle (EV) production and advanced driver-assistance systems (ADAS) expand, the demand for components like multi-layer ceramic capacitors (MLCCs) is increasing. LED usage, particularly in automotive applications, has recovered, further contributing to market growth. This trend is expected to continue as EV infrastructure improves and advanced safety systems become more widespread. Overall, the semiconductor industry is poised for ongoing expansion through AI, automotive innovations, and strong global demand.

China's Semiconductor Industry Rebounds in 2024 with Over 30 Projects Driving Innovation and Market Growth

China's semiconductor industry is witnessing a gradual recovery, driven by increasing downstream demand and progress in numerous projects across the sector. Over 30 semiconductor-related projects have advanced to stages such as contract signing, construction, and production. These projects span diverse areas, including electronic design automation (EDA), artificial intelligence (AI), advanced packaging, materials, equipment, third-generation semiconductors, chip design, CMOS sensors, and memory.

Key companies involved include Huahong, Semitronix, YASC, Skyverse, Hoshine, Smartsens, Sanan Semiconductor, and CFMEE. Industry reports indicate that revenue for companies in the mid-to-upper levels of the integrated circuit supply chain is improving, with AI driving revenue growth, particularly in the demand for acceleration chips like GPU and HBM.

Subsectors such as advanced packaging and materials are also benefiting from the recovery. New energy vehicles have increased demand for third-generation semiconductor materials, especially power devices like silicon carbide (SiC). TrendForce forecasts continued growth for SiC in high-power markets such as automotive and renewable energy, projecting the global SiC power device market to reach $9.17 billion by 2028.

Project Areas	Companies Involved	Key Market Trends
EDA	Huahong, Semitronix, YASC	Growth in design automation tools
AI	Skyverse	AI driving demand for GPU/HBM
Advanced Packaging	Huahong	Increased demand in packaging technology
Materials	Hoshine	High demand for new materials

General Market Insight

Project Areas	Companies Involved	Key Market Trends
Equipment	CFMEE	Growth in Semiconductor manufacturing equipment
Thrid-Generation Semiconductors	Sanan Semiconductor	High demand for SiC and other third-gen materials
Chip design	Huahong	Development in Chip architectures
CMOS Sensors	Smartsens	Advances in sensor technologies
Memory	Huahong	Increased memory production

Global Semiconductor Memory Market Set to Reach $127.5 Billion by 2028, Driven by Advancements in Smart Devices and 3D NAND-DRAM Technology

$127.5B
by 2028

The global semiconductor memory market is expected to grow from $101.27 billion in 2024 to $127.5 billion by 2028, with a compound annual growth rate (CAGR) of 5.9%. This growth is driven by the rising demand for smart devices, enterprise computing, and consumer electronics, as well as advancements in technologies such as 3D NAND-DRAM. Asia-Pacific leads the market, with key players like Micron, Samsung, and SK hynix driving innovation and competition across regions.

Opportunities Emerge as DDR4 Market Adapts to Shifting Demand and Competitive Pricing

The DDR4 memory market is navigating a period of transformation, with manufacturers responding to evolving demand by offering competitive pricing, including discounts of up to 15%. While challenges like inventory adjustments and low demand in PC and mobile applications persist, these market shifts open doors for buyers to secure favorable deals. As manufacturers adapt to changes in supply and demand dynamics, the DDR4 market is expected to stabilize, presenting new opportunities for growth and strategic partnerships in 2024 and beyond.

General Market Insight

Rebound Electronics Attended NEPCON Vietnam 2024 to Explore Market Trends and Opportunities

NEPCON Vietnam 2024, held from September 11 to 13 in Hanoi, highlighted the latest advancements in electronics manufacturing and technology. Organized by RX Tradex and Reed K. Fairs, the event brought together more than 300 electronics brands and companies, drawing over 10,000 visitors and 5,000 industry professionals. With a strong focus on trends such as Surface Mount Technology (SMT), intelligent manufacturing, and testing technologies, NEPCON Vietnam remains one of the most influential platforms for electronic innovation in the region.

Leading companies from across the globe showcased innovative solutions ranging from automation machinery to IoT devices. The event featured specialized seminars, industry networking events, and competitions focused on electronics assembly skills. Importantly, Rebound Senior Commercial Analyst, a key figure in electronic supply chains, attended NEPCON Vietnam 2024, contributing insights on market trends and innovations

Key Market Trends

- AI and IoT Integration: Internet of Things (IoT) and Artificial Intelligence (AI) technologies were central to the discussions. The combination of IoT and AI is transforming manufacturing processes, enabling smarter production and predictive maintenance.

- Supply Chain Innovations: With recent global supply chain disruptions, the adoption of blockchain and IoT in supply chain management has been accelerated to improve transparency and logistics efficiency.

- Sustainability: Companies showcased green solutions, such as recycling electronic components, optimizing energy usage in manufacturing, and using eco-friendly materials to meet environmental regulations

General Market Insight

Challenges

- Supply Chain Disruptions: Global logistical challenges continue to pressure electronics manufacturers to adopt more resilient practices.
- Technology Adaptation: Rapid advancements in AI and robotics require significant investments and adaptation, posing challenges for companies keeping up with technological shifts.
- Environmental Compliance: Increased environmental regulations necessitate investments in sustainable technologies, often adding to operational costs

NEPCON Vietnam 2024 served as a pivotal event for the electronics industry, offering insights into the future of manufacturing, the integration of AI and IoT, and the development of sustainable practices. It provided a platform for networking, collaboration, and strategic discussions, preparing businesses to navigate the evolving landscape of electronics manufacturing. In line with Rebound Electronics' commitment to keeping our customers informed about the latest trends in the semiconductor industry, we are actively participating in these events globally highlighting the key trends, challenges, and strategies surrounding the increasingly dynamic semiconductor industry landscape.

Semiconductor Supply Chain September 2024 Overview

In September 2024, the global semiconductor supply chain continued to evolve with key developments in production capabilities, partnerships, and market dynamics. Major players are addressing supply challenges and capacity expansion to meet growing demand, especially in sectors like electric vehicles (EVs), renewable energy, and artificial intelligence (AI).

Capacity Expansion

Companies like Onsemi are accelerating their investment in 8-inch silicon carbide (SiC) wafer production, doubling their efforts in high-growth areas such as EVs and AI data centers. Meanwhile, Panasonic has ramped up high-capacity EV battery production in Japan, positioning itself to supply key automakers like Tesla.

Geopolitical Influences

The U.S. CHIPS Act continues to reshape the semiconductor landscape, with Texas Instruments securing $4.6 billion in grants and loans for new manufacturing facilities in the U.S., highlighting efforts to bolster domestic semiconductor production.

Technological Advancements

Infineon introduced a 300mm gallium nitride (GaN) wafer technology breakthrough, aimed at improving efficiency, size, and cost for power electronics, reflecting the push for innovation across the supply chain.

Supply Chain Bottlenecks

Despite progress, companies are still dealing with supply chain challenges like rising SiC costs and market oversupply, particularly in EV sectors where demand has softened in the short term.

The overall outlook for the semiconductor supply chain remains positive, driven by strategic investments and innovations to meet future demands despite present hurdles.

General Market Insight

Latest Updates and News from Industry Leaders

AMD

- AMD will host "Advancing AI 2024" on October 10, showcasing next-gen Instinct accelerators, 5th Gen EPYC processors, and expanding AI solutions, with Chair and CEO Dr. Lisa Su leading the event.
- AMD has completed the $665 million acquisition of Silo AI to accelerate the development and deployment of AI models on AMD hardware, enhancing its AI capabilities with Silo AI's expertise in large-scale AI models and enterprise solutions
- AMD is rumored to launch its Ryzen 7 9800X3D 3D V-Cache CPU in late October 2024, with the high-end Ryzen 9 9950X3D and Ryzen 9 9900X3D expected to follow in early 2025.
- AMD is developing FSR4 with AI-driven frame generation to enhance performance and significantly boost battery life in handheld gaming devices like the ROG Ally and Legion Go.

Analog Devices

- Tata Group and Analog Devices have formed a strategic alliance to explore semiconductor and electronics manufacturing opportunities in India, focusing on integrating ADI's products into Tata's applications like EVs and network infrastructure, with plans for manufacturing in Gujarat and Assam.

Broadcom

- Broadcom has fixed a critical remote code execution (RCE) vulnerability (CVE-2024-38812) in VMware vCenter Server, allowing attackers to exploit unpatched servers via network packets, with administrators urged to apply security updates or restrict network access as a workaround.
- Broadcom has introduced the Sian2 chip, designed to power AI clusters' high-speed optical networks, offering double the bandwidth of its predecessor, improving network reliability through error mitigation, and reducing hardware and power costs.
- Broadcom has announced the general availability of its Sian™2 200G/lane DSP PHY, doubling bandwidth and enhancing connectivity for next-generation AI clusters with 200G/lane electrical and optical interfaces.

Diodes Inc.

- Diodes Incorporated has introduced the AH332xQ (unipolar) and AH352xQ (omnipolar) Hall effect switch ICs for automotive applications, offering a range of sensitivity options for proximity detection in functions such as seatbelt fastening and door latching, with robust protection features and reliable performance in harsh environments.
- Diodes Incorporated has launched the AL58221, a 12-channel constant-current LED driver designed for digital signage and display applications, offering high accuracy, adaptive pulse density modulation (APDM) for improved visual refresh rates, and support for cascading up to 1,030 devices, with availability starting at $0.37 in 1,000-piece quantities.
- Diodes Incorporated has introduced the PI3DPX1225Q, a 10Gbps automotive-compliant active crossbar multiplexer with a linear ReDriver™, offering low-latency connectivity for smart cockpits and rear-seat entertainment, supporting USB 3.2 and DisplayPort 2.1 signals with enhanced signal integrity and minimal jitter, available at $1.87 in 3,500-piece quantities.

Infineon

- Infineon has developed the world's first 300mm GaN wafer technology, enabling more efficient, smaller, and cost-effective power electronics with significantly higher chip production capacity.
- Infineon Technologies is using Fingerprint Cards' FPC1323 sensor in its Secora Pay Bio biometric payment card, integrating secure fingerprint authentication and enabling in-field enrolment, with support for Visa and Mastercard, to enhance convenience and security in payment transactions.
- Infineon announced plans to cut 1,400 jobs and relocate an additional 1,400 positions to lower-cost countries as part of its cost-saving "Step Up" program, following disappointing Q3 2024 results with a 9% revenue drop year-on-year, attributed to weak economic conditions.
- Infineon's new PASCO2V15 sensor uses photoacoustic spectroscopy (PAS) to precisely monitor indoor CO2 levels in a compact, energy-efficient design aimed at improving air quality in smart buildings

Intel

- Intel has exited the discrete PC graphics card market, leaving Nvidia with 88% market share and AMD with 12%.
- Qualcomm is reportedly considering a potential takeover of Intel, though no official offer has been made, as Intel faces challenges with declining profits, manufacturing issues, and competitive pressures from rivals like AMD and Nvidia.
- Intel has launched its Gaudi 3 AI accelerator, offering slower performance than Nvidia's H100 but with a significant price advantage, aiming to compete through lower total cost of ownership (TCO) as AI demand transforms data centers.

Kyocera

- Kyocera has broken ground on a new plant in Nagasaki, Japan, to expand production of fine ceramic components and semiconductor packages, with operations set to begin in 2026, investing approximately 68 billion yen (469 million USD) by 2028.
- IKEA, Kyocera, and OOCL have partnered on a biofuel-powered voyage using a 24% biofuel blend, leveraging blockchain technology to track carbon savings, advancing sustainability in the shipping industry.
- Kyocera has launched a $60 million venture fund, Kyocera Venture Fund-I (KVF-I), targeting US and EMEA startups in sectors like energy, IT, healthcare, AI, and semiconductors, with investment sizes ranging from $200,000 to $2 million.

Lattice

- Lattice Semiconductor has expanded its small FPGA portfolio with new logic-optimized Certus™-NX FPGA devices, offering enhanced power efficiency, small form factors, and high reliability, targeting applications in communications, computing, industrial, and automotive sectors.

Murata

- Murata has unveiled the world's smallest multilayer ceramic capacitor (MLCC) in the 006003-inch size (0.16mm x 0.08mm), achieving a 75% volume reduction from its previous smallest model, aimed at enabling higher-density component mounting in compact electronic devices like smartphones and wearables.
- Murata has accelerated its climate goals, moving its target for 100% renewable energy (RE100) forward by 15 years to FY2035 and aiming for carbon neutrality by FY2040 for its operations and FY2050 across its entire supply chain, reinforcing its commitment to combating climate change and promoting sustainability.

Nexperia

- Nexperia workers plan to strike after 82% of union members voted in favor, protesting the dismissal of around 600 workers last year.
- Nexperia has introduced the NXF6501-Q100, NXF6505A-Q100, and NXF6505B-Q100 push-pull transformer drivers, offering up to 90% efficiency and 6W power delivery, designed for automotive and industrial applications with low-noise, low-EMI isolated power supplies, and comprehensive internal protection features.
- Nexperia has expanded its NextPower 80/100V MOSFET portfolio with new LFPAK devices optimized for low RDS(on) and reduced Qrr, offering high efficiency and low EMI for applications such as servers, power supplies, and industrial equipment, with plans to further enhance the range later this year.

NVIDIA

- The upcoming Nvidia GeForce RTX 5090 GPU is rumored to draw up to 600W of power, potentially requiring two 16-pin power connectors, meaning users may need a new PSU with dual 12V-2x6 sockets to support this power-hungry graphics card.
- NetApp has unveiled an advanced generative AI data vision that integrates NVIDIA AI software with NetApp's intelligent ONTAP data infrastructure, enabling enterprises to securely access and leverage vast data stores across hybrid multi-cloud environments to fuel next-generation AI applications.

NXP

- NXP Semiconductor has introduced the MC33777, a battery junction box IC for EVs and hybrid vehicles, integrating current, voltage, and temperature sensing with fuse emulation and pyrotechnic switch control to enhance safety and efficiency, while reducing component count and system costs.
- NXP Semiconductors plans to invest over $1 billion in India to double its R&D efforts, focusing on automotive and other industries, as part of India's push to expand its semiconductor industry and become a global chipmaking hub.
- Raam Memory Technologies has announced a collaboration with NXP Semiconductors to integrate its CMOS-compatible embedded DRAM, called Gain-Cell Random Access Memory (GCRAM), which offers 50% area savings, and 90% lower power consumption compared to SRAM, enhancing NXP's future memory solutions.

Onsemi

- Onsemi is targeting double growth in 2024 by expanding its SiC production capacity and strengthening partnerships with global automakers, while advancing sustainability efforts.
- OmniVision, STMicroelectronics, and Onsemi have enhanced their image sensor portfolios with innovations for AR/VR/MR and industrial applications, focusing on size, efficiency, and advanced technology integration.
- Onsemi has signed a multi-year deal with Volkswagen Group to supply a scalable silicon carbide-based power solution for the next-generation electric vehicle traction inverters, with plans to expand European manufacturing for enhanced supply chain integration
- Onsemi is rapidly advancing its 8-inch silicon carbide (SiC) technology, targeting double growth in 2024 as it strengthens partnerships with automakers and expands global production capacity, including new investments in South Korea and the Czech Republic.

Panasonic

- Panasonic Avionics and Collins Aerospace discussed the future of in-flight entertainment (IFE), focusing on sustainability, innovative technologies, and collaborative efforts to advance aviation industry trends and solutions.
- Panasonic's new AK-UCX100 4K studio camera offers high-quality, versatile, and IP-based solutions for streamlined live event and studio productions.
- Panasonic Energy has finalized preparations to mass-produce high-capacity 4680 EV batteries, offering five times the capacity of its smaller batteries, at its renovated Wakayama plant for automakers like Tesla.
- The Panasonic Toughbook G2 Mk3 features a 47% longer battery life, a 1,000 nits display, and rugged durability, powered by the new Intel Meteor Lake-U processor
- Panasonic aims to expand CO2 refrigeration adoption in Japanese supermarkets, leveraging energy efficiency benefits and

Rapidus

- Japanese chip startup Rapidus is seeking to raise ¥100 billion from existing and new investors, including Toyota, Sony, and banks, to fund its chip development and construction of a foundry in Hokkaido, aiming to challenge Taiwan Semiconductor Manufacturing Co. by 2027.
- Rapidus's supply chain is taking shape as Taiyo Nippon Sanso prepares to supply industrial gases by November 2024, supporting the company's goal of mass-producing 2nm chips by 2027 at its Hokkaido factory, with green hydrogen production also planned for future semiconductor manufacturing.

Renesas

- Renesas has expanded its R-Car family with the power-efficient R-Car V4M and V4H SoCs, offering scalable AI processing for entry-level ADAS applications, with strong performance, power efficiency, and software reusability, targeting Level 1 and Level 2 ADAS markets.
- Renesas has completed its acquisition of Altium, a leader in PCB design software, aiming to create an integrated electronics design and lifecycle management platform to accelerate innovation and broaden market accessibility.
- The RX23E-B microcontroller offers a high-speed 24-bit delta-sigma A/D converter with 125kSPS, reduced noise, and integrated analog features, ideal for precise industrial sensor measurements.

Samsung

- Hyundai Motor, Kia, and Samsung Electronics have partnered to enhance connectivity between software-defined vehicles (SDVs) and smartphones, developing a next-generation infotainment system and user-centered mobility ecosystem.
- Samsung has unveiled the 990 EVO Plus SSDs with PCIe 4.0 support, offering up to 7,250MB/s read and 6,300MB/s write speeds, 73% greater power efficiency, and impressive performance for gaming, content creation, and business tasks, available in capacities up to 4TB this fall.
- Intel and Samsung are facing delays in their fab projects due to financial and operational challenges, strengthening TSMC's position as the leading global semiconductor manufacturer with ongoing global expansion.

Siemens

- Siemens introduced Innovator3D IC, a Multiphysics cockpit for efficient 3D IC and chiplet design, prototyping, and analysis.
- Siemens and Merck have entered a strategic collaboration to advance digital transformation in manufacturing, focusing on smart, modular systems to enhance production speed, flexibility, and sustainability in industries like healthcare, life sciences, and electronics.
- Siemens Mobility is building a $60 million rail car facility in Horseheads, New York, to produce electric high-speed trains for Brightline West, creating 300 jobs and supporting the development of a low-carbon rail system connecting Las Vegas and California by 2028.

ST Microelectronics

- Edge Impulse and STMicroelectronics have partnered to enhance edge AI deployments by integrating their technologies, with new AI solutions expected to be unveiled soon.
- STMicroelectronics has introduced its fourth-generation SiC MOSFETs, enhancing power efficiency and compactness for EV traction inverters, with 750 V devices available now and 1200 V devices expected in 2025.
- STMicroelectronics experienced a sharp decline in Q2 earnings, with revenue dropping 25.3% and net income down 64%, citing weak demand in the automotive sector and lower-than-expected industrial orders, while adjusting its full-year revenue forecast amid industry-wide struggles.

TDK

- TDK's new ERU33M high-current chokes use a novel alloy powder core to enhance current density and energy storage for automotive and industrial power applications.
- TDK launches the Tronics AXO314, a robust and precise closed-loop digital MEMS accelerometer for high dynamics industrial applications, ideal for land, sea, and air surveying and mapping.

Toshiba

- Toshiba has launched its 1200V third-generation SiC Schottky barrier diodes, featuring low forward voltage and enhanced efficiency, targeting industrial equipment like photovoltaic inverters, EV charging stations, and switching power supplies.
- Toshiba has launched the TDS4A212MX multiplexer and TDS4B212MX demultiplexer switches, supporting up to 32Gbps high-speed differential signaling with low power consumption and compact design for PCIe 5.0, USB4 Ver.2, and Thunderbolt 4 applications.
- Toshiba has signed an MOU with Indonesia's PLN Nusantara Power to explore the application of CO_2 capture technology at thermal power plants, aiming to support Indonesia's goal of carbon neutrality by 2060 through the potential adoption of CCS equipment.

Texas Instruments

- Texas Instruments has been awarded $1.6 billion in CHIPS Act funding to support its $18 billion investment in building three semiconductor fabs in Texas and Utah, expected to create 2,000 jobs and produce essential analog and embedded processing chips.
- Texas Instruments has unveiled MagPack packaging technology for six new DC-DC power modules, offering up to 50% size reduction, improved thermal and EMI performance, and enhanced efficiency for high-performance applications.
- The SIA praises the $1.6 billion CHIPS Act incentives for Texas Instruments to boost U.S. semiconductor production with new fabs in Texas and Utah.

TSMC

- TSMC and Samsung are reportedly in early discussions with the UAE about developing semiconductor fabs, potentially worth over $100 billion, but face challenges related to the region's water supply, skilled labor shortages, and geopolitical tensions amid the US-China trade war.
- TSMC has begun small-scale production of Apple's A16 Bionic chips at its Arizona Fab 21 facility using 4nm technology, marking the first U.S.-made mobile processors for Apple, ahead of the fab's full-scale operations slated for 2025.

Vishay

- Vishay Intertechnology has announced a global restructuring plan, involving the closure of three plants and layoffs of around 530 employees, with the goal of optimizing its manufacturing footprint and realizing annual cost savings of at least $23 million by the end of 2026.
- Vishay Intertechnology has expanded its inductor product line with 1,800 new SKUs across 70 series, enhancing flexibility and performance while investing in global capacity upgrades to better serve the telecom, industrial, and consumer markets.

ANALOG		PRICING TREND	LEAD TIME TREND	LEAD TIME (WEEKS)
Standard	Amplifiers & Comparators	→	→	18+
	Analog Interface	→	→	18+
	Power Management	→	→	18+
	Converters	→	→	18+
Standard Analog Total		→	→	18+
Advanced		→	→	18+

MOS MICROLOGIC		PRICING TREND	LEAD TIME TREND	LEAD TIME (WEEKS)
MPU		→	→	18+
MCU	8 Bit & Lower	→	→	12-18
	16 Bit	→	→	18+
	32 Bit & Higher	→	→	12-18
MCU Total		→	→	18+
Automotive MCU		→	→	28+
DSP		→	→	28+

PROGRAMMABLE LOGIC	PRICING TREND	LEAD TIME TREND	LEAD TIME (WEEKS)
	→	→	18+

STANDARD LOGIC	PRICING TREND	LEAD TIME TREND	LEAD TIME (WEEKS)
Timing Products	→	→	28+
Interface	→	→	28+
Connectivity	→	→	28+
Standard Logic	→	→	12-18

POWER	PRICING TREND	LEAD TIME TREND	LEAD TIME (WEEKS)
FET	→	→	18+
IGBT	→	→	28+
Rectifier	→	↑	12-18
Other Power	↓	↑	12-18

MEMORY	PRICING TREND	LEAD TIME TREND	LEAD TIME (WEEKS)
Flash – NOR	→	→	**18+**
Flash – NAND	↑	→	**12-18**
eMMC	↑	→	**12-18**
EEPROM	→	↓	**4-10**
DRAM	↑	→	**12-18**
SRAM	→	→	**4-10**
Solid State Drives	↑	→	**18+**

SENSORS	PRICING TREND	LEAD TIME TREND	LEAD TIME (WEEKS)
	→	→	18

OPTO	PRICING TREND	LEAD TIME TREND	LEAD TIME (WEEKS)
LEDs (Low Power)	→	→	**4-10**
LEDs (Mid Power)	→	→	**4-10**
LEDs (High Power)	→	→	**12-18**
Couplers	→	→	**18+**
Fibre-Optic	→	→	**18+**
Infrared	→	→	**18+**
Other Opto	→	→	**18+**

DISCRETE	PRICING TREND	LEAD TIME TREND	LEAD TIME (WEEKS)
Small Signal	→	→	**12-18**
RF	→	→	**12-18**

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↔	Stable
↗	Increasing
↙	Decreasing
SMA	Selective Market Adjustment
EOL	End-of-Life

Click on a category below:

Analog
High - End
Battery
Interconnect
Connectivity
Opto / Lighting
Discrete
Memory
Electromechanical
Passives

Analog

MANUFACTURER	PRODUCT	LEAD TIME (WEEKS)	TREND	PRICING	COMMENTS
Analog devices	Sensors	18-22	↔	↗	
ams	Sensors	10-26	↔	SMA	
Bosch Sensortec	Sensors	8-14	↔	↔	
Diodes Incorporated	Multi- Source Analog/Power	12-22	↙	↔	
	Switching Regulators	12-20	↙	↔	
FTDI Chip	Interface	12-16	↙	↔	
Infineon	Sensors	6-28	↔	↔	
	Switching Regulators	16-28	↙	↔	
	Analog and Power for Automotive (CAN/LIN/Smart FET)	22-42	↙	↔	
Maxlinear	Interface	10-14	↙	↔	
Melexis	Sensors	14-62	↔	SMA	
Microchip	Signal Chain (Amplifiers and Data Converters)	6-12	↙	↔	
	Timing	10-14	↙	↔	
	Switching Regulators	10-22	↔	↔	
Monolithic Power Systems	Switching Regulators	14-26	↔	↔	
NXP	Sensors	18-54	↔	↔	
	Interface	18-22	↙	↔	
	Analog and Power for Automotive (CAN/LIN/Smart FET)	14-22	↙	↔	

MANUFACTURER	PRODUCT	LEAD TIME (WEEKS)	TREND	PRICING	COMMENTS
Onsemi	Sensors	20-54	↔	SMA	
	Signal Chain (Amplifiers and Data Converters)	12-22	↙	↔	
	Timing	20-26	↙	↔	
	Multi- Source Analog/Power	12-22	↙	↔	
	Switching Regulators	12-22	↔	↔	
Panasonic	Sensors	18-28	↗	↔	
Pericom Saronix-eCera	Timing	16-26	↙	↔	
Power Integrations	Switching Regulators	18-20	↔	↔	
Renesas	Signal Chain (Amplifiers and Data Converters)	14-22	↙	↔	
	Timing	14-26	↙	↔	
	Interface	14-22	↙	↔	
	Switching Regulators	16-26	↙	↔	
ROHM	Sensors	26-54	↗	↗	
	Switching Regulators	14-28	↔	↔	
ST Microelectronics	Sensors	22-36	↔	↔	
	Signal Chain (Amplifiers and Data Converters)	12-22	↙	↔	
	Multi- Source Analog/Power	12-22	↙	↔	
	Switching Regulators	12-22	↔	↔	
	Analog and Power for Automotive (CAN/LIN/Smart FET)	22-32	↙	↔	
TE Sensor Solutions	Sensors	18-54	↗	SMA	
Texas Instruments	Regulators	18-22	↔	↔	
	Sensors	18-22	↔	↔	
	Interface	18-22	↔	↔	
Vishay	Sensors	26-54	↗	↔	

Batteries

MANUFACTURER	PRODUCT	LEAD TIME (WEEKS)	TREND	PRICING	COMMENTS
Alium Batteries	Lithium Ion	22-24	↔	↔	
Energizer	Alkaline	12-14	↔	↔	
	Lithium Metal	16-18	↔	↔	
	Silver Oxide	10-12	↔	↔	
GP Batteries	Alkaline	16-18	↔	↗	
	Lithium Metal	20-22	↔	↗	
	Lithium Ion	18-20	↔	↗	
	Nickle Metal Hydride	12-14	↔	↔	
	Lead Acid	10-12	↔	↔	
	Carbon Zinc	10-12	↔	↔	
Panasonic	Alkaline	12-14	↔	↔	
	Lithium Metal	16-18	↙	↔	
	Nickle Metal Hydride	10-12	↔	↔	
	Carbon Zinc	10-12	↔	↔	
Rayovac	Alkaline	10-12	↔	↔	
	Lithium Metal	12-14	↔	↔	
	Nickle Metal Hydride	10-12	↔	↗	
	Carbon Zinc	10-12	↔	↔	
Renata Batteries	Lithium Metal	16-18	↔	↔	
	Lithium Ion	22-24	↔	↔	
	Nickle Metal Hydride	12-14	↔	↗	
	Silver Oxide	10-12	↔	↔	
	Carbon Zinc	10-12	↔	↔	

Batteries

MANUFACTURER	PRODUCT	LEAD TIME (WEEKS)	TREND	PRICING	COMMENTS
Tadiran Batteries	Lithium Metal	14-16	↔	↔	
	Alkaline	12-14	↔	↔	
	Lithium Metal	20-26	↔	↔	
VARTA	Lithium Ion	34-40	↔	↔	
	Nickle Metal Hydride	12-14	↔	↗	

REBOUND ELECTRONICS
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Connectivity

MANUFACTURER	PRODUCT	LEAD TIME (WEEKS)	TREND	PRICING	COMMENTS
AMS	RFID	22	↗	↔	
CEL	802.15.4/Zigbee Modules	28-34	↔	↔	
	Small Signal, Schottky Diodes, PIN Diodes, Bipolar Transistors, FETs/PHEMTs, Amplifiers, Mixers & Modulators, VCOs, SS Bipolar Transistors, Wideband Transistors	32	↔	↔	
Infineon + Cypress	Bluetooth Modules	18-26	↔	↔	Cypress is now Infineon
	Small Signal, Schottky Diodes, PIN Diodes, Bipolar Transistors, FETs/PHEMTs, Amplifiers, Mixers and Modulators, VCOs, SS Bipolar Transistors, Wideband Transistors	14-18	↔	↔	
Fibocom	Cellular Modules	18-22	↔	↔	
Kyocera AVX	Antennas	10-12	↔	↔	
Laird Connectivity	Wi-Fi Modules	18-38	↔	↔	
	Antennas	14-18	↗	↔	
	LoRa	~32-54	↗	↔	
Linx Technologies	Cellular Modules	8-12	↔	↔	
	Antennas	12-14	↗	↔	
	Transceivers/Receivers	12-14	↗	↔	
Melexis	Transceivers/Receivers	18	↔	↔	
	RFID	16-18	↔	↔	
Microchip	Wi-Fi Modules	14-22	↔	↔	
	Bluetooth Modules	14-22	↔	↔	
	Transceivers/Receivers	14-22	↔	↔	
	LoRa	18	↔	↔	
MultiTech	Cellular Modules	18-22	↔	↔	
	LoRa	~22	↔	↔	

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
Murata	Wi-Fi Modules	28-52	↔	↔	
	Bluetooth Modules	28-52	↔	↔	
	Small Signal, Schottky Diodes, PIN Diodes, Bipolar Transistors, FETs/PHEMTs, Amplifiers, Mixers and Modulators, VCOs, SS Bipolar Transistors, Wideband Transistors	14-22	↔	↔	
	LoRa	32-42	↔	↔	
Nearson	Antennas	10-12	↔	↔	
NXP	Multi-Protocol/Chip Solutions	28-38	↔	↗	
	Transceivers/Receivers	26	↔	↔	
	RFID	16	↔	↔	Parts on allocation
	High Power IC's	14-18	↔	↔	
	Small Signal, Schottky Diodes, PIN Diodes, Bipolar Transistors, FETs/PHEMTs, Amplifiers, Mixers and Modulators, VCOs, SS Bipolar Transistors, Wideband Transistors	14-18	↔	↔	
Onsemi	Bluetooth Modules	18-32	↔	↔	
Panasonic	Bluetooth Modules	18-28	↔	↔	
	RFID	16-18	↔	↔	
Pulse Electronics	Antennas	10-12	↔	↔	
Semtech	Transceivers/Receivers	12-14	↗	↔	
	LoRa	10-18	↔	↔	
Sierra Wireless	Multi-Protocol/Chip Solutions	42-48	↔	↔	
	Cellular Modules	10-12	↔	↔	Intel based radios are at 52 weeks
Silex Technology	Wi-Fi Modules	22-42	↔	↔	
ST Microelectronics	Bluetooth Modules	12-14	↔	↔	
	Transceivers/Receivers	14	↔	↔	Capacity constraints on Spirit Radio
	RFID	22	↔	↔	ST25R39xx on allocation
	GPS	14	↔	↔	
	High Power IC's	22-32	↔	↔	
	LoRa	12-14	↔	↔	

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
Synapse Wireless	802.15.4/Zigbee Modules	20-22	↔	↔	
Taoglas	Antennas	22-24	↗	↔	
TDK	Small Signal, Schottky Diodes, PIN Diodes, Bipolar Transistors, FETs/PHEMTs, Amplifiers, Mixers and Modulators, VCOs, SS Bipolar Transistors, Wideband Transistors	14-22	↔	↔	
Thales	Cellular Modules	14-22	↔	↔	
U-Blox	Bluetooth Modules	14-28	↔	↔	
	Cellular Modules	14-28	↔	↔	Parts are on allocation, lead time is 26+
	GPS	14-28	↔	↔	Parts are on allocation and increasing in cost
	WiFi Modules	14-28	↔	↔	

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Discrete

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
Diodes Inc.	Low Voltage MOSFETS	10-18	↔	SMA	
	TVS Diodes	8-14	↙	↔	
	Bridge Rectifiers	10-18	↔	↔	
	Schottky Diodes	10-14	↔	↔	
	Rectifiers	10-16	↔	↔	
	Switching Diodes	10-14	↔	↔	
	Small Signal MOSFETS	10-14	↔	↔	
	Zener Diodes	10-14	↔	↔	
	Bipolar Transistors	10-14	↔	↔	
	Digital Transistors	10-14	↔	↔	
	General Purpose Transistors	10-14	↔	↔	
	Logic	10-12	↔	↔	
EATON	ESD	12-14	↔	↔	
	Fuses	10-14	↔	↔	
	Clips and Holders	12-16	↔	↔	
Everlight	Optocoupler Components	16-20	↔	↔	
Fairchild	Rectifiers	18-52	↙	↔	
	Optocoupler Components	12-20	↔	↔	
Infineon	Low Voltage MOSFETS	12-22	↙	SMA	
	High Voltage MOSFETS	12-28	↙	↔	
	IGBTs	14-54	↙	↙	
	Wide Bandgap Mosfets	10-42	↔	↙	
	Digital Transistors	8-32	↔	↔	
	General Purpose Transistors	8-52	↔	↔	
	Mil-Aero Transistors	22-32	↔	↔	
Texas Instruments	Logic	18-22	↔	↔	

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
Isocom Components	Optocoupler Components	4-6	↔	↔	
IXYS	High Voltage MOSFETS	52-56	↔	↔	
	IGBTs	52-56	↔	↔	
Keystone	Clips and Holders	12-18	↔	SMA	
Kyocera	Varistors	16-20	↔	↔	
Lite-On	Optocoupler Components	14-16	↔	↔	
Littelfuse	ESD	12-14	↔	↔	
	Diode Arrays	12-14	↔	↔	
	Varistors	16-28	↗	↔	
	Wide Bandgap Mosfets	32-54	↔	↔	
	Fuses	10-14	↔	↔	
	PTC Fuses	10-14	↔	↔	
	Clips and Holders	12-16	↔	↔	
	Thyristors/Triacs	18-22	↔	↔	
	TVS Diodes	8-14	↙	↔	
	Sensors	18-32	↔	SMA	
Micro Commercial Components	Low Voltage MOSFETS	12-26	↙	↔	
	High Voltage MOSFETS	14-30	↔	↔	
	ESD	12-14	↔	↔	
	TVS Diodes	10-12	↔	↔	
	Schottky Diodes	10-14	↔	↔	
	Switching Diodes	10-14	↔	↔	
	Small Signal Mosfets	12-16	↔	↔	
	Zener Diodes	12-16	↔	↔	
	Bipolar Transistors	10-16	↔	↔	
	General Purpose Transistors	10-16	↔	↔	

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
Microchip	High Voltage Mosfets	6-34	↔	↔	
	Wide BandGap Mosfets	10-26	↔	↔	
Microsemi	High Voltage MOSFETS	44-54	↔	↔	
	IGBTs	44-54	↔	↔	
	Mil-Aero Diodes	28-54	↔	↔	
	Mil-Aero Transistors	34-62	↔	↔	
Nexperia	Low Voltage MOSFETS	8-18	↔	SMA	
	ESD	8-12	↔	↔	
	Schottky Diodes	8-10	↔	↔	
	Switching Diodes	8-10	↔	↔	
	Small Signal MOSFETS	8-10	↔	↔	
	Zener Diodes	8-10	↙	↔	
	Bipolar Transistors	8-10	↔	↔	
	Digital Transistors	8-10	↔	↔	
	General Purpose Transistors	8-10	↔	↔	
	Logic	8-10	↔	↔	
ON Semiconductor	Low Voltage MOSFETS	12-48	↙	SMA	
	High Voltage MOSFETS	16-44	↙	SMA	
	ESD	14-22	↙	↔	
	Wide Bandgap Mosfets	12-50	↔	↔	
	Schottky Diodes	12-38	↔	↔	
	Rectifiers	18-32	↔	↔	
	Switching Diodes	12-42	↔	SMA	
	Small Signal MOSFETS	14-48	↔	SMA	
	Zener Diodes	12-48	↔	SMA	
	Bipolar Transistors	12-42	↔	SMA	
	Digital Transistors	12-42	↔	SMA	
	General Purpose Transistors	12-42	↔	SMA	
	Logic	10-20	↔	↔	
ProTek Devices	Diode Arrays	10-14	↔	↔	
Renesas	Optocoupler Components	20-22	↔	SMA	
ROHM	High Voltage MOSFETS	14-24	↔	↔	
	Wide Bandgap Mosfets	22-30	↔	↔	
	Schottky Diodes	14-22	↔	↔	
	Switching Diodes	14-22	↔	↔	
	Digital Transistors	14-18	↔	↔	
	General Purpose Transistors	14-18	↔	↔	

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
Schurter	Fuses	22-42	↔	↔	
	Clips and Holders	22-32	↔	↔	
Semtech	Diode Arrays	10-14	↔	↔	
ST Microelectronics	Low Voltage MOSFETS	15-43	↙	↔	
	High Voltage MOSFETS	16-42	↙	↔	
	IGBTs	16-54	↙	↔	
	ESD	35-54	↙	↔	
	Wide Bandgap Mosfets	35-54	↔	↔	
	Thyristors/Triacs	18-20	↔	↔	
	TVS Diodes	18-20	↔	↔	
	Rectifiers	16-18	↔	SMA	
	Bipolar Transistors	14-26	↔	↔	
TDK EPCOS	Varistors	16-28	↔	↔	
TE Connectivity	PTC Fuses	10-14	↔	↔	
Vishay	Low Voltage MOSFETS	15-44	↔	SMA	
	High Voltage MOSFETS	13-34	↔	SMA	
	TVS Diodes	18-20	↔	SMA	
	Bridge Rectifiers	10-12	↔	SMA	
	Rectifiers	10-12	↔	SMA	
	Zener Diodes	12-16	↔	↔	
	Optocoupler Components	6-14	↔	↔	

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INDUSTRIES

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Automotive

Aerospace & Defence

Renewable Energy

Medical

Electromechanical

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
Abracon	Timing	14-54+	↙	SMA	Tuning Forks-32.7668KHZ and 40-52+ weeks, TCXO's are on allocation due to AKM fire
ADDA	Fans	22-26	↔	↔	
Alps Electric	Switches	26-34	↔	↔	
American Zettler	Relays	18-32	↔	↔	
Bivar	Hardware	12-18	↔	↔	
Boyd	Fans	14-16	↗	↗	
	Heatsinks	18-26	↔	↗	
C&K	Switches	14-32	↔	↔	
Churod Electronics	Relays	10-32	↔	↔	
Citizen Finedevice	Timing	14-54	↔	↔	Tuning Forks-32.7668KHZ and 40-52+ weeks, TCXO's are on allocation due to AKM fire
COSEL	Power Supplies (AC/DC)	14-38	↙	↔	
	Power Supplies (DC/DC)	14-38	↔	↔	
CTS	Switches	10-12	↔	↔	
	Timing	12-32	↔	↔	Tuning Forks-32.7668KHZ and 40-52+ weeks, TCXO's are on allocation due to AKM fire
CUI Inc	Power Supplies (AC/DC)	26-54+	↔	↔	
	Power Supplies (DC/DC)	14-38	↙	↔	
	Heatsinks	12-14	↔	↗	
Delta	Fans	42-54	↔	↔	
Diodes Inc	Timing	10-14	↔	↔	Tuning Forks-32.7668KHZ and 40-52+ weeks, TCXO's are on allocation due to AKM fire

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
E-Switch	Switches	14-16	↔	↔	
ECS Inc.	Timing	14-42	↙	SMA	Tuning Forks-32.7668KHZ and 40-52+ weeks, TCXO's are on allocation due to AKM fire
EPSON Electronics America	Timing	14-28	↔	↔	Tuning Forks-32.7668KHZ and 40-52+ weeks, TCXO's are on allocation due to AKM fire
Essentra Components	Hardware	14-16	↗	↗	
Fox	Timing	12-42+	↔	↔	Tuning Forks-32.7668KHZ and 40-52+ weeks, TCXO's are on allocation due to AKM fire
Grayhill	Switches	14-26	↔	↗	
Heyco	Hardware	12-14	↔	↔	
Hongfa	Relays	18-32	↔	SMA	
Infineon	Relays	42-54	↔	↗	
IXYS	Relays	12-32	↔	↔	
Keystone	Hardware	14-16	↔	↔	
Kyocera International	Timing	18-30	↙	↔	Tuning Forks-32.7668KHZ and 40-52+ weeks, TCXO's are on allocation due to AKM fire
MEAN WELL	Power Supplies (AC/DC)	16-20	↔	↔	
Microchip	Timing	14-28	↔	↗	Tuning Forks-32.7668KHZ and 40-52+ weeks, TCXO's are on allocation due to AKM fire
Murata	Timing	10-12	↔	↔	Tuning Forks-32.7668KHZ and 40-52+ weeks, TCXO's are on allocation due to AKM fire
Murata Power Solutions	Power Supplies (AC/DC)	10-12	↔	↗	

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
NKK Switches	Switches	12-20	↔	↔	
NMB	Fans	28-42	↔	↔	
Ohmite	Fans	12-14	↗	↗	
Orion Fans	Fans	18-20	↔	↔	
Panasonic	Relays	16-32	↔	↔	
	Switches	12-14	↔	↔	
Qualtek	Fans	22-26	↔	↔	
Raltron	Timing	12-42	↔	↔	Tuning Forks-32.7668KHZ and 40-52+ weeks, TCXO's are on allocation due to AKM fire
RECOM	Power Supplies (AC/DC)	18-42	↔	↔	
	Power Supplies (DC/DC)	16-38	↔	↔	
Rosenberg	Fans	20-22	↔	↔	
Schneider Electric	Relays	18-20	↔	↔	
Song Chuan	Relays	26-38	↔	↔	
SUNON	Fans	32-44	↔	↔	
TE Connectivity Sensors	Relays	14-16	↔	↔	All stable except the IM ready Series-allocation 52+ weeks
	Switches	12-14	↔	↔	
Vicor	Power Supplies (AC/DC)	28-54	↗	↗	
	Power Supplies (DC/DC)	28-54	↗	↗	
Wakefield Thermal	Heatsinks	12-14	↔	↗	
Wall Industries	Power Supplies (AC/DC)	10-12	↔	↔	
	Power Supplies (DC/DC)	10-12	↔	↔	
ZF Electronics	Switches	20-22	↔	↗	

REBOUND ELECTRONICS
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High - End

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
AZ Displays	LCD's	14-16	↙	↔	
Compulab	SOM	18-26	↙	↙	
Cypress	8 bit MCU	12-18	↙	↔	
	32 bit MCU	12-54	↙	↔	
	USB	44-54	↙	↔	
	Automotive	34-48	↔	↔	
Formerica	Fibre Optic Transceivers	14-18	↙	↔	
Infineon	Automotive	Allocation	↔	↔	
iWave Systems	SOM	28-32	↙	↙	
Lattice Semiconductor	FPGA	18-26	↙	↙	
Microchip	8 bit MCU	6-14	↔	↔	
	32 bit MCU	6-20	↔	↙	
	PHY/ Ethernet	8-14	↔	↔	
	USB	6-12	↔	↔	
	32 bit MPU	6-22	↔	↔	
Microsemi	FPGA	10-32	↔	↔	
NXP	8 bit MCU	15-42	↔	↔	
	32 bit MCU	15-42	↔	↔	
	Automotive	20-54	↔	↔	
	32 bit MPU	20-42	↔	↔	
	Network Processors	20-44	↔	↔	
Renesas RA	32 bit MCU	20	↙	↔	
Renesas	8 bit MCU	14	↔	↔	
	32 bit MCU	14	↔	↔	
	Automotive	48	↔	↔	
	32 bit MPU	14	↔	↔	
Sharp	LCDs	30-32	↙	↔	
ST Microelectronics	8 bit MCU	12-26	↗	↔	
	Automotive	42-54	↔	↔	
	32 bit MPU	18-22	↔	↔	
	STM32F0- 32 bit MCU	12-14	↔	↔	
	STM32F1- 32 bit MCU	18-22	↔	↔	
	STM32L- 32 bit MCU	18-22	↔	↔	
	Balance 32 bit MCU	12-14	↗	↙	
	STM32F2/F4/F7/H7	12-22	↗	↙	
Texas Instruments	MCUs & Processors	30-32	↔	↔	
Xilinx	FPGA	18-22	↔	↔	
Zilog	8 bit MCU	26-42	↔	↔	

Interconnect

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
Adam Tech	I/O Connectors	18-20	↔	↗	
	PCB Connectors	18-20	↔	↗	
Altech Corp.	Terminal Blocks & Crimps	14	↔	↔	
Amphenol Communications Solutions	D-Sub Connectors	10-12	↔	↔	
	Data & Telecom	10-12	↔	↔	
	PCB Connectors	10-12	↔	↔	
	FFC/FPC	10-12	↔	↔	
Amphenol Sine System	Circular Connectors	10-22	↔	↗	
ASSMAN WSW Components	Data & Telecom	22	↔	↔	
	PCB Connectors	22	↔	↔	
	IC Sockets	22	↔	↔	
Bulgin	Circular Connectors	18-20	↔	↗	
EDAC	PCB Connectors	16-24	↔	↔	
Global Connector Technology	PCB Connectors	10-12	↔	↗	
	FFC/FPC	10-12	↔	↗	

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
HALO Electronics	Data & Telecom	14-20	↔	↔	
HARTING	PCB Connectors	12-14	↔	↔	
Hirose Electric	PCB Connectors	10-18	↙	↔	
	RF Connectors	10-18	↙	↔	
	FFC/FPC	10-18	↙	↔	
JST	PCB Connectors	18	↔	↔	
Mil-Max	PCB Connectors	6-8	↔	↗	
	IC Sockets	6-8	↔	↗	
Ouipiin	PCB Connectors	16-22	↔	↔	
Sullins	PCB Connectors	8-10	↔	↔	
TE Connectivity	Automotive Connectors	14-18	↔	↔	
	Circular Connectors	14-18	↔	↔	
	Relays	14-18	↔	↔	
	Data & Telecom	14-18	↔	↔	
	PCB Connectors	14-18	↔	↔	
	RF Connectors	14-18	↔	↔	
	IC Sockets	14-18	↔	↔	
	Terminal Blocks & Crimps	14-18	↔	↔	
	Lighting Connectors	14-18	↔	↔	
WAGO	Terminal Blocks & Crimps	16	↔	↔	
	Lighting Connectors	16	↔	↔	
WECO	Terminal Blocks & Crimps	22	↔	↗	

Lighting Solutions & Opto

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
Bridgelux	Chip On Board (CoB)	8-10	↔	↔	
Dialight	Indication LEDs	12-18	↔	↔	
	6V (LED Optics)	12-18	↔	↔	
Everlight	Automotive LEDs (AEC-Q101 Certified)	10-12	↔	↔	
	Infrared Components/ LED	16-18	↔	↔	
	Indication LEDs	16-18	↔	↔	
	UV LEDs	10-12	↔	↔	
Excellence Optoelectronics Inc.	Automotive LEDs (AEC-Q101 Certified)	10-12	↔	↔	
General Luminaire	Standard Light Engines (Level 2 Boards)	16-18	↔	↔	
Inolux	Indication LEDs	8-10	↔	↔	
Kingbright	LED Displays	12-14	↔	↔	
	Indication LEDs	10-12	↔	↔	
Lite-On	Infrared Components/ LED	16-18	↔	↔	
	LED Displays	16-18	↔	↔	
	Indication LEDs	18-22	↔	↔	
Lumex	LED Displays	18	↔	↔	
	Indication LEDs	10-16	↔	↔	
Lumileds	Illumination High Power LEDs (White)	10-16	↔	↔	
	Illumination High Power LEDs (Colors)	10-16	↔	↔	
	Illumination High Power LEDs (White & Colors)	10-12	↔	↔	
	Horitcultural Mid Power LEDs (White & Colors)	10-12	↔	↔	
	Automotive LEDs (AEC-Q101 Certified)	16-18	↔	↔	
	Chip On Board (CoB)	10-12	↔	↔	
	Standard Light Engines (Level 2 Boards)	20-28	↔	↔	
	Infrared Components/ LED	28	↔	↔	
	UV LEDs	14-18	↔	↔	
Meanwell	LED Drivers	12-22	↔	↔	
Murata	Lighting Controls	28-32	↔	↔	

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
Nichia	Illumination High Power LEDs (White)	8-12	↔	↔	
	Illumination High Power LEDs (Colors)	8-12	↔	↔	
	Illumination High Power LEDs (White & Colors)	10-12	↔	↔	
	Horitcultural Mid Power LEDs (White & Colors)	10-12	↔	↔	
	Chip On Board (CoB)	14-16	↔	↔	
ROHM	Infrared Components/ LED	8-10	↔	↔	
	Indication LEDs	12-14	↔	↔	
Samsung LED	Illumination High Power LEDs (White)	8-10	↔	↔	
	Illumination High Power LEDs (White & Colors)	10-12	↔	↔	
	Horitcultural Mid Power LEDs (White & Colors)	10-12	↔	↔	
	Chip On Board (CoB)	8-10	↔	↔	
	Standard Light Engines (Level 2 Boards)	8-10	↔	↔	
Seoul Semiconductor	Illumination High Power LEDs (White)	8-10	↔	↔	
	Illumination High Power LEDs (White & Colors)	8-10	↔	↔	
	Horitcultural Mid Power LEDs (White & Colors)	8-10	↔	SMA	
	Chip On Board (CoB)	10-12	↔	↔	
	Standard Light Engines (Level 2 Boards)	12-14	↔	↔	
Seoul Viosys	UV LEDs	10-12	↔	↔	
Stanley Electric	LED Displays	14	↔	↔	
	Indication LEDs	12-14	↔	↔	
TE Connectivity	6A (Heat Sinks, LED Holders)	22-52	↔	↔	
TT Electronics- Optek Technology	Infrared Components/ LED	28-46	↔	↗	
VCC	Indication LEDs	14	↔	↔	
Vishay	Infrared Components/ LED	10-22	↙	↔	
	Indication LEDs	10-32	↔	↗	
	UV LEDs	16-18	↔	↔	

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Memory

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
ADATA	Memory Modules	8-10	↔	↗	
	eMMC	8-10	↗	↗	
	Memory Cards	10-12	↔	↗	
	Solid State Drives (SSD)	10-14	↗	↗	
Alliance Memory	PC (Commodity) DRAM	4-22	↔	↔	
	Mobile RAM	10-18	↙	↔	
	SRAM	10-32	↙	↔	
	NOR Flash	14-22	↔	↔	
	NAND Flash	10-26	↙	↔	
	eMMC	10-14	↔	↔	
Cypress	SRAM	14-54	↙	↔	
	NOR Flash	14-28	↙	↔	
	FRAM & NVSRAM	14-28	↙	↔	
Everspin Technologies	MRAM	14-30	↔	↔	
Greenliant	NOR Flash	10-18	↔	↔	
	eMMC	14-20	↗	↗	
	Memory Cards	10-18	↔	↗	
	Solid State Drives (SSD)	10-18	↗	↗	
Kingston	PC (Commodity) DRAM	4-6	↔	↔	
	Memory Modules	4-8	↔	↔	
	eMMC	6-8	↗	↗	
	Memory Cards	4-12	↔	↗	
	Solid State Drives (SSD)	6-10	↗	↗	
Macronix	NOR Flash	10-14	↔	SMA	
	NAND Flash	10-14	↔	SMA	
	eMMC	20-28	↔	↗	Parts on allocation, MXIC is not quoting and not taking new orders for the time being

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
Microchip	SRAM	6-14	↙	↔	
	NOR Flash	6-28	↙	↔	
	EEPROM	6-28	↙	↔	
	EPROM	14-28	↔	↗	
Onsemi	SRAM	22-42	↔	↔	
	EEPROM	22-32	↙	↔	
Renesas	SRAM	20-24	↙	↔	
	NOR FLASH	20-24	↙	↔	
	DATA FLASH	30-32	↙	↔	
Samsung LED	PC (Commodity) DRAM	54-56	↔	↔	
	Memory Modules	54-56	↔	↔	Parts on allocation, Samsung is not quoting and not taking new orders for the time being
	eMMC	54-56	↔	↔	
	Solid State Drives (SSD)	54-56	↔	↔	
SkyHigh Memory	SLC NAND Flash	8-12	↙	↔	
	eMMC	10-14	↔	↙	
STMicroelectronics	EEPROM	8-14	↔	↔	Now on allocation

Passives

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
Apl Delevan	Inductors	16-18	↙	↔	
Cornell Dubilier Electronics	Electrolytic	24-48	↔	↗	
	Capacitor	28-42	↙	↗	
CTS	Resistor Networks	18-42	↔	↔	
Eaton	Capacitors - Supercapacitors	12-22	↙	↔	
	Inductors	22-32	↙	↔	
ELNA	Capacitors - Supercapacitors	32-54+	↔	↔	
HALO Electronics	Inductors	16-18	↙	↔	
Murata	Filters	14-18	↔	↔	
	Inductor / Transformers	14-22	↔	↔	
	Surface Mount General Capacitors- Ceramic (Less than 1 uf)	12-16	↔	↔	
	Surface Mount General Capacitors- Ceramic (Greater than 1 uf)	12-14	↔	↔	
	Leaded Capacitors- Ceramic	18-20	↔	↔	
	Specialty Capacitors	18	↔	↔	
	Surface Mount General Capacitors	16-18	↔	↔	
NIC Components	Electrolytic	24-32	↙	↔	
	Filters	16-22	↔	↔	
	Inductors	16-22	↔	↔	
	Fixed Resistors	14-20	↔	↔	
		20-22	↔	↔	
	Surface Mount General Capacitors - Ceramic (Greater than 1 uf)	14-16	↔	↔	
	Leaded Capacitors - Ceramic	28-30	↔	↔	

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
Nichicon	Electrolytic	20-32	↙	↔	
Panasonic	Electrolytic	20-32	↙	↔	
	Capacitors- Polymer Tantalum	12-14	↗	↔	
	Inductors / Transformers	20-24	↙	↔	
	Fixed Resistors	22-32	↙	↔	
	Resistor Networks	20-30	↔	↔	
Paktron Capacitors	Capactors- Film	14-18	↔	↗	
Samsung Electro-Mechanics	Fixed Resistors	46-48	↔	↔	
	Surface Mount General Capacitors- Ceramic (Less than 1 uf)	46-48	↔	↔	
	Surface Mount General Capacitors – Ceramic (Great than 1 uf)	14-16	↔	↔	
	Surface Mount General Capacitors-Ceramic *Automotive Upgrade	14-16	↔	↔	
Stackploe Electronics	Fixed Resistors	18-26	↔	↔	
Sumida	Inductors	22-26	↔	↔	
Taiyo Yuden	Surface Mount General Capacitors- Ceramic (Less than 1 uf)	20-22	↔	↔	
	Surface Mount General Capacitors- Ceramic (Greater than 1 uf)	22-24	↔	↔	
	Surface Mount General Capacitors-Ceramic *Automotive Upgrade	22-24	↔	↔	
TDK	Filters	14-18	↗	↗	
	Surface Mount General Capacitors- Ceramic (Less than 1 uf)	22-26	↔	↔	
	Surface Mount General Capacitors- Ceramic (Greater than 1 uf)	26-38	↗	↔	
	Surface Mount General Capacitors-Ceramic *Automotive Upgrade	26-32	↔	↔	
TDK EPCOS	Capacitors- Film	26-54+	↔	↔	
	Filters	14-18	↗	↔	
	Inductors / Transformers	18-22	↔	↔	

MANUFACTURER	PRODUCT	LEAD TIME (WKS)	TREND	PRICING	COMMENTS
TT Electronics- BI Technologies	Trimmers & Pots	42-54	↔	↗	
TT Electronics- IRC	Fixed Resistors	22-54	↗	↗	
United Chemi-Con	Electrolytic	24-36	↙	↔	
Viking	Surface Mount General Capacitors- Ceramic (Less than 1 uf)	18-20	↔	↔	
	Surface Mount General Capacitors- Ceramic (Greater than 1 uf)	16-18	↔	↔	
Vishay	Trimmers & Pots	12-22	↔	↔	
	Capacitors- Film	14-22	↙	↔	
	Capacitors- Supercapacitors	14-16	↔	↔	
	Capacitors- Tantalum Molded	18-20	↙	↔	
	Capacitors- Tantalum Conformals	14-16	↔	↔	
	Capacitors- Polymer Tantalum	14-16	↗	↔	
	Inductors / Transformers	14-16	↙	↔	
	Fixed Resistors	12-22	↙	↔	
	Surface Mount General Capacitors - Ceramic (Less than 1 uf)	16-18	↙	↔	
	Leaded Capacitors - Ceramic	20-26	↙	↔	
	Specialty Capacitors	28-36	↙	↔	
WIMA	Capacitors- Film	14-18	↙	↔	
Wurth Elektronik	Inductors / Transformers	20-22	↔	↔	
Yageo	Fixed Resistors	20-22	↔	↔	
	Resistor Networks	22-26	↔	↔	
	Surface Mount General Capacitors - Ceramic (Less than 1 uf)	16-18	↔	↔	
	Surface Mount General Capacitors - Ceramic (Greater than 1 uf)	16-18	↔	↔	
	Surface Mount General Capacitors- Ceramic *Automotive Upgrade	16-18	↔	↔	

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Market Insights Q3 2024

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